EEC 118 Lecture #8: CMOS Logic Transient Characteristics

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- Quiz 2 on Monday, April 26
- Midterm on Monday, May 3

- Covers material through Lecture (Monday 4/26)

- HW4 due Friday, 4PM in box, Kemper 2131
- Lab 3, Part 2 report due next week

Outline

- Review: Static CMOS Logic
- Finish equivalent inverter discussion
- Combinational MOS Logic Circuits: Rabaey 6.1-6.2, 7.1-7.3 (Kang & Leblebici, 7.1-7.4)

Review: Static CMOS

- Complementary pullup network (PUN) and pulldown network (PDN)
- Only <u>one</u> network is on at a time
- PUN: PMOS devices
 - Why? $V_{OH} = V_{DD}$
- PDN: NMOS devices

$$-$$
 Why? V_{OL} = 0 V

PUN and PDN are *dual* networks



Review: Dual Networks

 Dual networks: parallel connection in PDN = series connection in PUN, viceversa

- If CMOS gate implements logic function F:
 - PUN implements function F
 - PDN implements function G = \overline{F}



Review: Equivalent Inverter

- Represent complex gate as inverter for delay estimation, VTC analysis
- Use worse-case conditions for delays
- Example: NAND gate
 - Worse-case (slowest) pull-up: only 1 PMOS "on"
 - Pull-down: both NMOS "on"



Graph-Based Dual Network

- Use graph theory to help design gates
 - Mostly implemented in CAD tools
- Draw network for PUN or PDN
 - Circuit nodes are vertices
 - Transistors are edges



F

B

Graph-Based Dual Network (2)

- To derive dual network:
 - Create new node in each enclosed region of graph
 - Draw new edge intersecting each original edge
 - Edge is controlled by inverted input





Propagation Delay Analysis - The Switch Model



(assuming that C_L dominates!)

- Model transistors as switches with series resistance
- Resistance R_{on} = average resistance for a transition
- Capacitance C_L = average load capacitance for a transition (same as we analyzed for transient inverter delays)



- Depends strongly on the operating region
- For hand analysis use a fixed value of R which it the average of the two end points of the transition
- Similar to the previous approach of averaging currents

EXAMPLE: For t_{pHL} for an inverter, the R_{on} is:

$$R_{on} = \frac{1}{2} (R_{NMOS}(V_{out} = V_{DD}) + R_{NMOS}(V_{out} = V_{DD}/2))$$
$$= \frac{1}{2} \left(\left(\frac{V_{DS}}{I_D} \right)_{V_{out}} = V_{DD} + \left(\frac{V_{DS}}{I_D} \right)_{V_{out}} = V_{DD}/2 \right)$$

Delay estimation using switch-level model (for general RC circuit):



• For fall delay t_{phl} , $V_0 = V_{DD}$, $V_1 = V_{DD}/2$

$$t_{p} = RC \ln\left(\frac{V_{1}}{V_{0}}\right) = RC \ln\left(\frac{\frac{1}{2}V_{DD}}{V_{DD}}\right)$$
$$t_{p} = RC \ln(0.5)$$
$$t_{phl} = 0.69R_{n}C_{L}$$
$$t_{plh} = 0.69R_{p}C_{L}$$
$$\leftarrow \text{Standard RC-delay} \text{equations from literature}$$

Numerical Examples

• Example resistances for 1.2 μ m CMOS

 $V_{DD} = 5V$, W/Leff=1 (W/L_{eff}=2 is a minimum sized device 1.8µm/0.9µm) $L_{eff} = 1.2µm-2(.15µm)=0.9µm$

$$\begin{split} R_n(W/L_{eff} = 2) &= (5 \text{ V} / 0.46 \text{ mA} + 2.5 \text{ V} / 0.29 \text{ mA}) / 2 = 9.7 \text{ k}\Omega \text{ (for } t_{pHL}) \\ & | \\ R_n(W/L_{eff} = 1) = 9.7 * 2 = 19.4 \text{ k}\Omega \text{ (for } t_{pHL}) \end{split}$$

 $R_p(W/L_{eff}=6) = (5 \text{ V} / 0.57 \text{ mA} + 2.5 \text{ V} / 0.24 \text{ mA}) / 2 = 9.6 \text{ k}\Omega \text{ (for } t_{pLH})$

 $R_p(W/L_{eff} = 1) = 9.6 * 6 = 57.6 \text{ k}\Omega \text{ (for } t_{pLH})$

SOLVE RC NETWORK TO DETERMINE DELAYS

Analysis of Propagation Delay



2-input NAND

- 1. Assume $R_n = R_p$ = resistance of minimum sized NMOS inverter
- 2. Determine "Worst Case Input" transition (Delay depends on input values)
- 3. Example: t_{pLH} for 2 input NAND
 - Worst case when only ONE PMOS Pulls up the output node
 - For 2 PMOS devices in parallel, the resistance is lower

$$t_{\rho LH} = 0.69 R_{\rho} C_{L}$$

4. Example: *t_{pHL}* for 2input NAND - Worst case : TWO NMOS in series

$$t_{pHL} = 0.69(2R_n)C_L$$

Design for Worst Case



Here it is assumed that $R_p = R_n$

Fan-In and Fan-Out



Fan-Out

Number of logic gates connected to output (2 FET gate capacitances per fan-out)

<u>Fan-In</u>

Number of logical inputs Quadratic delay term due to: 1. Resistance increasing 2. Capacitance increasing for t_{pHL} (series NMOS)

 t_p proportional to $a_1FI + a_2FI^2 + a_3FO$

- Increase Transistor Sizing:
 - Works as long as Fan-out capacitance dominates self capacitance (S/D cap increases with increased width)
- Progressive Sizing:



Fast Complex Gates - Design Techniques (2)

• Transistor Ordering Place last arriving input closest to output node





Fast Complex Gates - Design Techniques (3)

Improved Logic Design



Note Fan-Out capacitance is the same, but Fan-In resistance lower for input gates (fewer series FETs)

Fast Complex Gates - Design Techniques (4)

• Buffering: Isolate Fan-in from Fan-out



Keeps high fan-in resistance isolated from large capacitive load $C_{\rm L}$

4 Input NAND Gate



In1In2In3 In4

Capacitances in a 4 input NAND Gate



Cgd5+Cgd7+Cgd8+2Cgd6(Miller)+Cdb5+Cdb6+Cdb7+Cd b8 +Cgd1+ Cdb1+ Cgs1+ Csb1+ 2Cgd2+ Cdb2+ Cw

Csb₄

 $In_4 = \frac{1}{4}$

Cgs₄

Next Topic: Sequential Logic

- Basic sequential circuits in CMOS
 - RS latches, transparent latches, flip-flops
 - Alternative sequential element topologies
 - Pipelining